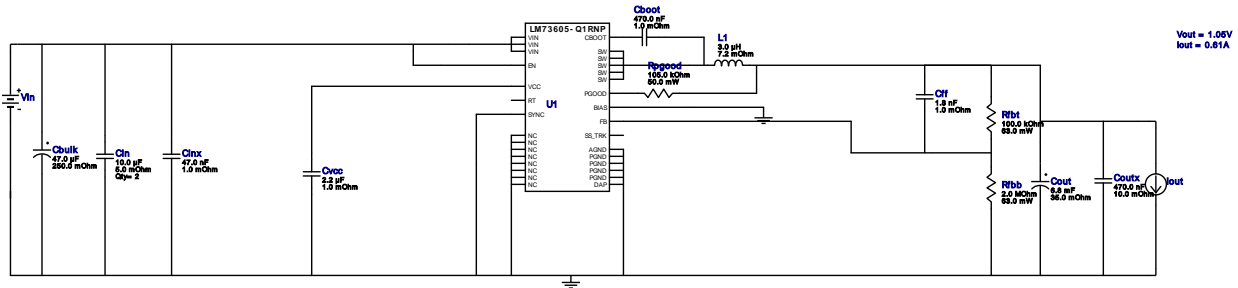


WEBENCH® Design Report

Design : 7631 LM73605QRNPRQ1
LM73605QRNPRQ1 4.5V-5.5V to 1.05V @ 0.61A


1. The input capacitor included in the BOM only contains a small filter capacitor that should be placed near the IC. Depending on where the power supply is laid out in the system additional bulk capacitance may need to be added to filter the line ripple.
2. If there is no VinTyp specified, WEBENCH will use the VinMax value. To change the VinTyp value, click on the "Change Design Inputs" button under the Optimization Tuning knob. In some applications, while the design requires the input voltage to be a wide range, for a majority of the time, it is operating at a much lower voltage than the maximum input voltage. Sizing the inductor based on the maximum input voltage may yield an inductance much larger than typically needed, causing a larger footprint for the overall design. At the same time, components such as the input capacitor must be rated based on the maximum input voltage. WEBENCH now supports the use of this additional input voltage specification.
3. This regulator device is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application. View WEBENCH(R) Disclaimer.

Design Alerts

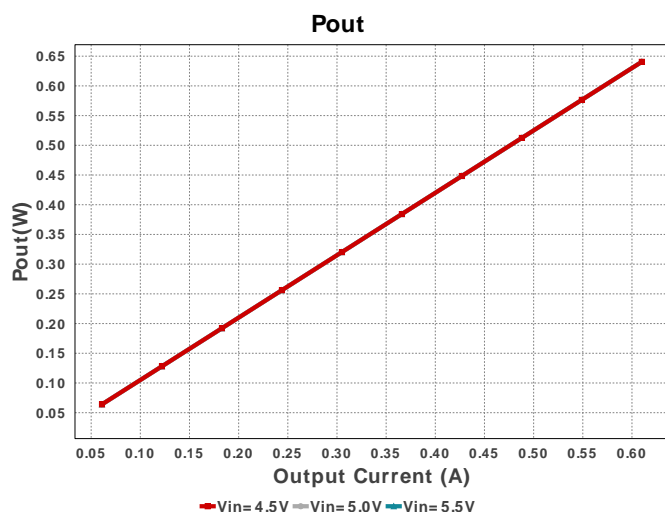
Component Selection Information

As light load performance of the device is not modeled, Efficiency and power dissipation charts are disabled and operating values are not displayed for PFM mode of operation. The LM73605-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.

Electrical BOM

| Name | Manufacturer | Part Number | Properties | Qty | Price | Footprint |
|-------|---------------------------|-----------------------------------|--|-----|--------|-----------------------------|
| Cboot | MuRata | GRM155R60J474KE19D Series= X5R | Cap= 470.0 nF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 0.0 A | 1 | \$0.02 | 0402 3 mm ² |
| Cbulk | AVX | TPSB476K010R0250 Series= TPS | Cap= 47.0 uF ESR= 250.0 mOhm VDC= 10.0 V IRMS= 525.0 mA | 1 | \$0.18 | 3528-21 17 mm ² |
| Cff | MuRata | GRM216R71E182KA01D Series= X7R | Cap= 1.8 nF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A | 1 | \$0.01 | 0805 7 mm ² |
| Cin | Samsung Electro-Mechanics | CL32B106KBJNNWE Series= X7R | Cap= 10.0 uF ESR= 5.0 mOhm VDC= 50.0 V IRMS= 0.0 A | 2 | \$0.17 | 1210_270 15 mm ² |
| Cinx | MuRata | GRM155R71E473KA88D Series= X7R | Cap= 47.0 nF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A | 1 | \$0.01 | 0402 3 mm ² |

| Name | Manufacturer | Part Number | Properties | Qty | Price | Footprint |
|--------|-------------------|--------------------------------------|---|-----|--------|--|
| Cout | Panasonic | EEV-FK0J682M Series= FK | Cap= 6.8 mF ESR= 35.0 mOhm VDC= 6.3 V IRMS= 1.8 A | 1 | \$0.70 |  SM_RADIAL_J16 399 mm ² |
| Coutx | MuRata | GRM188R70J474KA01D Series= X7R | Cap= 470.0 nF ESR= 10.0 mOhm VDC= 6.3 V IRMS= 2.91 A | 1 | \$0.03 |  0603 5 mm ² |
| Cvcc | Taiyo Yuden | EMK212BJ225KG-T Series= X5R | Cap= 2.2 uF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A | 1 | \$0.02 |  0805 7 mm ² |
| L1 | Bourns | SRU1048-3R0Y | L= 3.0 uH 7.2 mOhm | 1 | \$0.40 |  SRU1048 144 mm ² |
| Rfbb | Vishay-Dale | CRCW04022M00FKED Series= CRCW..e3 | Res= 2.0 MOhm Power= 63.0 mW Tolerance= 1.0% | 1 | \$0.01 |  0402 3 mm ² |
| Rfbt | Vishay-Dale | CRCW0402100KFKED Series= CRCW..e3 | Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0% | 1 | \$0.01 |  0402 3 mm ² |
| Rpgood | Yageo | RC0201FR-07105KL Series= ? | Res= 105.0 kOhm Power= 50.0 mW Tolerance= 1.0% | 1 | \$0.01 |  0201 2 mm ² |
| U1 | Texas Instruments | LM73605QRNPRQ1 | Switcher | 1 | \$2.95 |  RNP0030A 48 mm ² |



Operating Values

| # | Name | Value | Category | Description |
|----|-----------|-----------------------|--------------------|---|
| 1. | ICThetaJA | 15.25 degC/W | IC | IC junction-to-ambient thermal resistance |
| 2. | BOM Count | 14 | System Information | Total Design BOM count |
| 3. | FootPrint | 670.0 mm ² | System Information | Total Foot Print Area of BOM components |
| 4. | Iout | 610.0 mA | System Information | Iout operating point |

| # | Name | Value | Category | Description |
|-----|----------------|----------|--------------------|--|
| 5. | Mode | PFM | System Information | Conduction Mode |
| 6. | Pout | 640.5 mW | System Information | Total output power |
| 7. | Total BOM | \$4.69 | System Information | Total BOM Cost |
| 8. | Vin | 5.5 V | System Information | Vin operating point |
| 9. | Vout | 1.05 V | System Information | Operational Output Voltage |
| 10. | Vout Actual | 1.05 V | System Information | Vout Actual calculated based on selected voltage divider resistors |
| 11. | Vout Tolerance | 1.998 % | System Information | Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable |

Design Inputs

| Name | Value | Description |
|---------|------------|------------------------|
| Iout | 610.0 m | Maximum Output Current |
| VinMax | 5.5 | Maximum input voltage |
| VinMin | 4.5 | Minimum input voltage |
| Vout | 1.05 | Output Voltage |
| base_pn | LM73605-Q1 | Base Product Number |
| source | DC | Input Source Type |
| Ta | 30.0 | Ambient temperature |

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

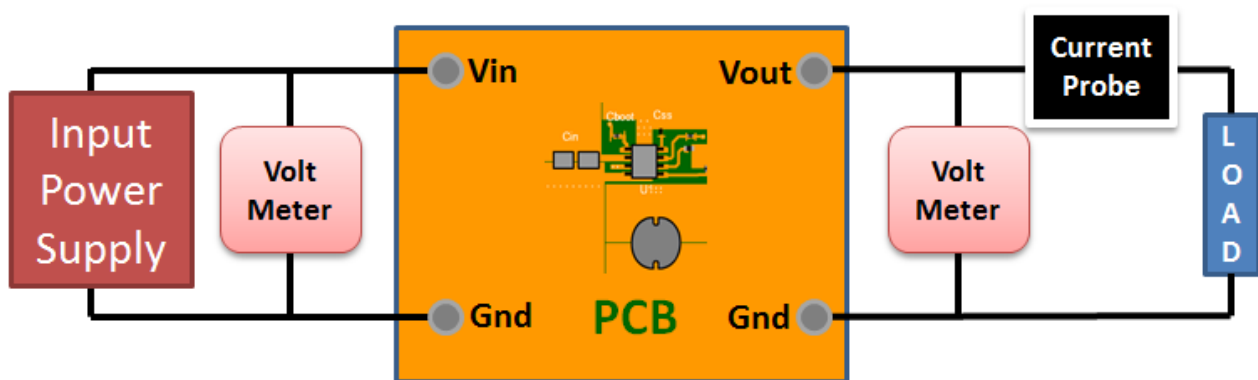
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 4.5V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. The LM73605-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.
2. Master key : B9C964572EBB957B[v1]
3. **LM73605-Q1** Product Folder : <http://www.ti.com/product/LM73605> : contains the data sheet and other resources.

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